

Towards wide-frequency substrate model of advanced FDSOI MOSFET

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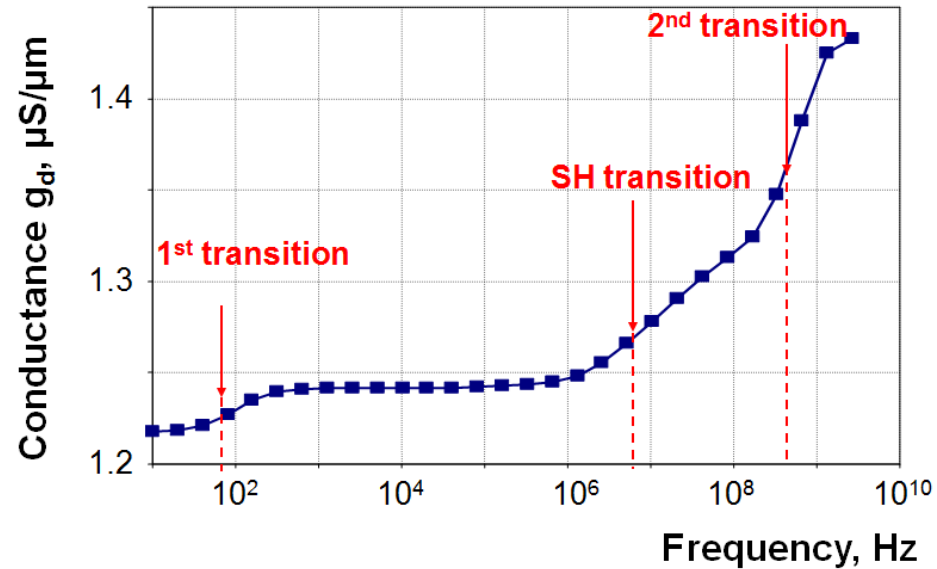


Outline

- Introduction and motivation
- Method
- Results
 - Accumulation
 - Inversion
- Summary and future work

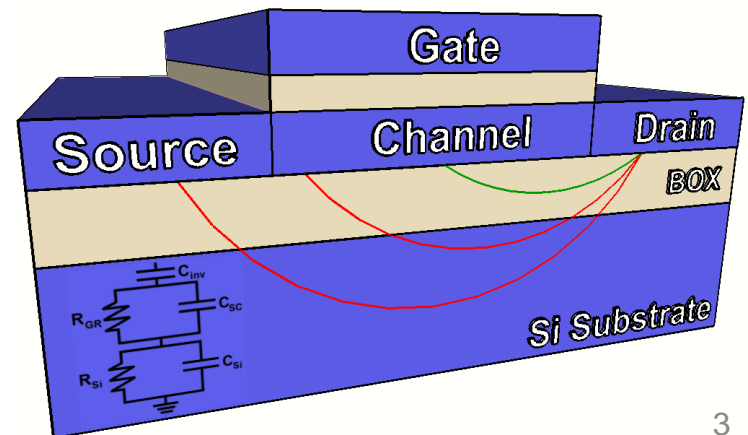
Introduction

- In SOI MOSFETs g_d and therefore A_v are frequency dependent (not desirable for analogue circuits)
- Self-heating and substrate effects are the main mechanisms
- Self-heating is well known
- Substrate effects frequency dependence is not widely known

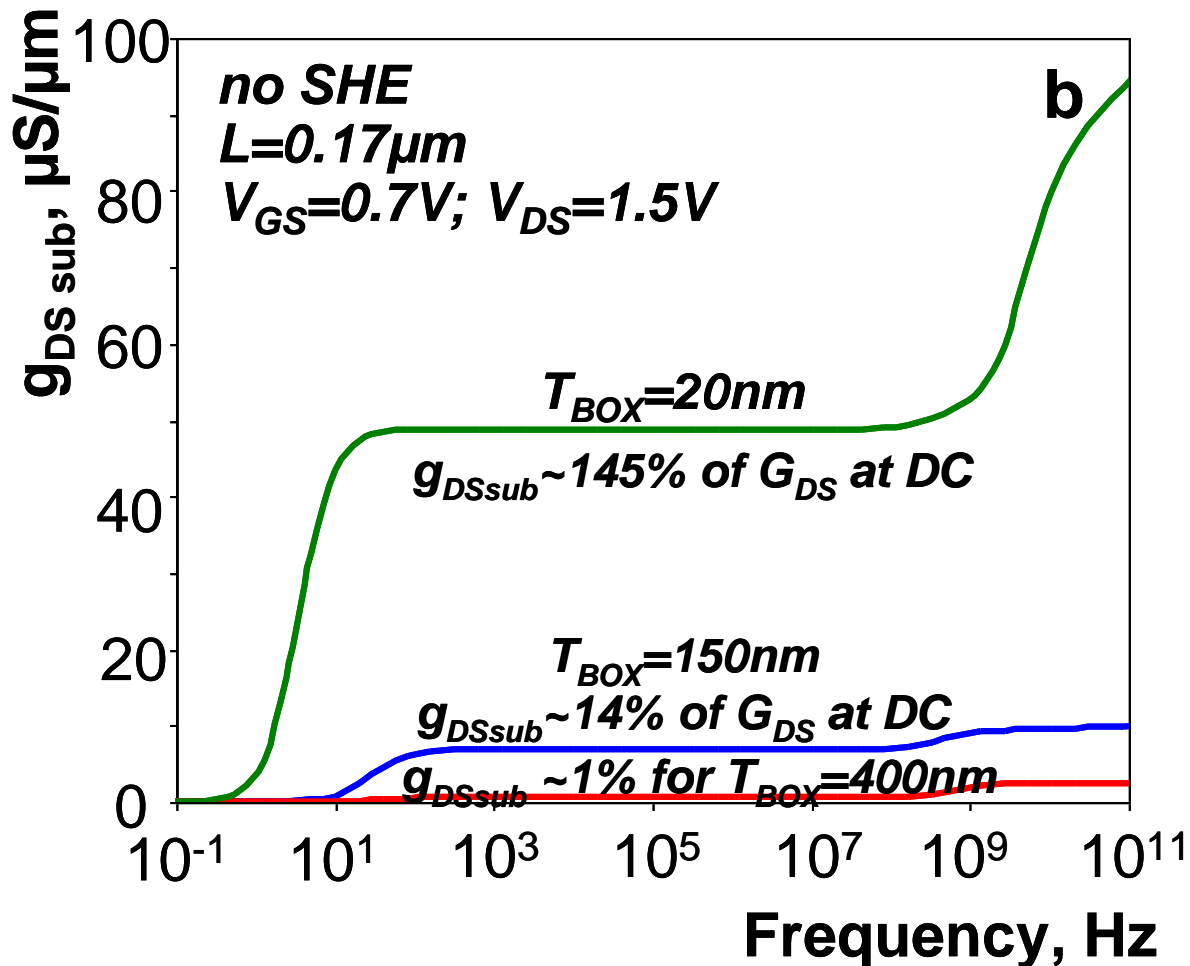


$$g_d(f) = g_{\text{intr}} + \Delta g_{\text{FB}}(f) + \Delta g_{d_SH}(f) + \Delta g_{d_SUB}(f)$$

\nearrow CLM, DIBL \nearrow PDSOI only

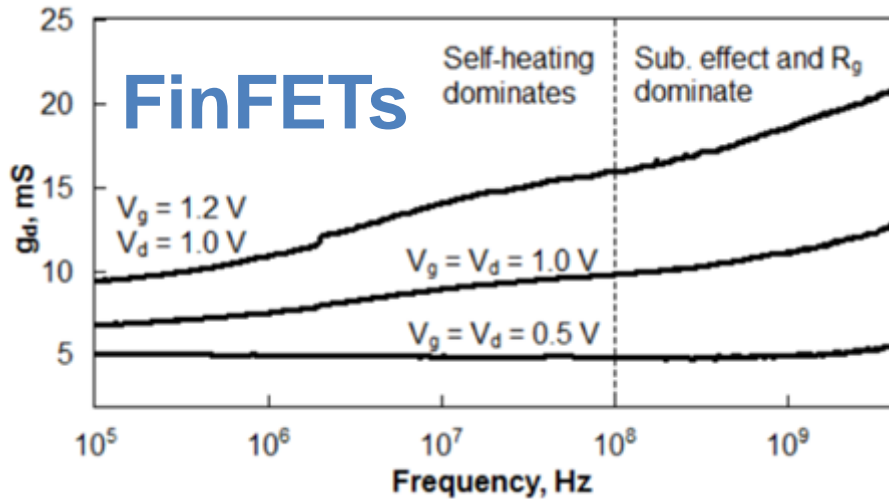


BOX Thinning

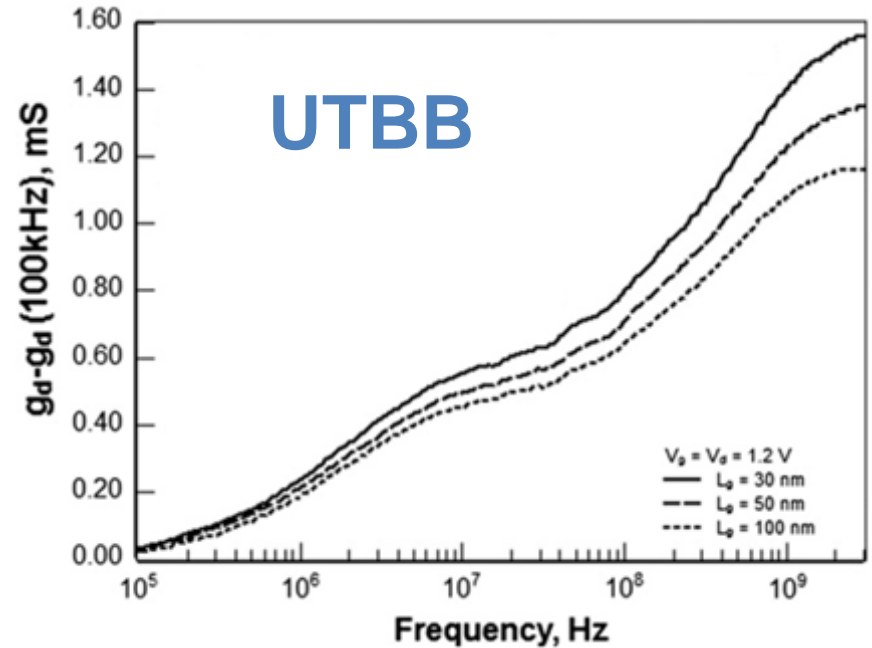


- BOX scaling results in strong increase of substrate-related effects
- BOX scaling with V_d scaling are expected to change the dominant effect in the frequency response

Experimental Confirmation



[Makovejev *et al.*, Intl. SOI conf. 2012]



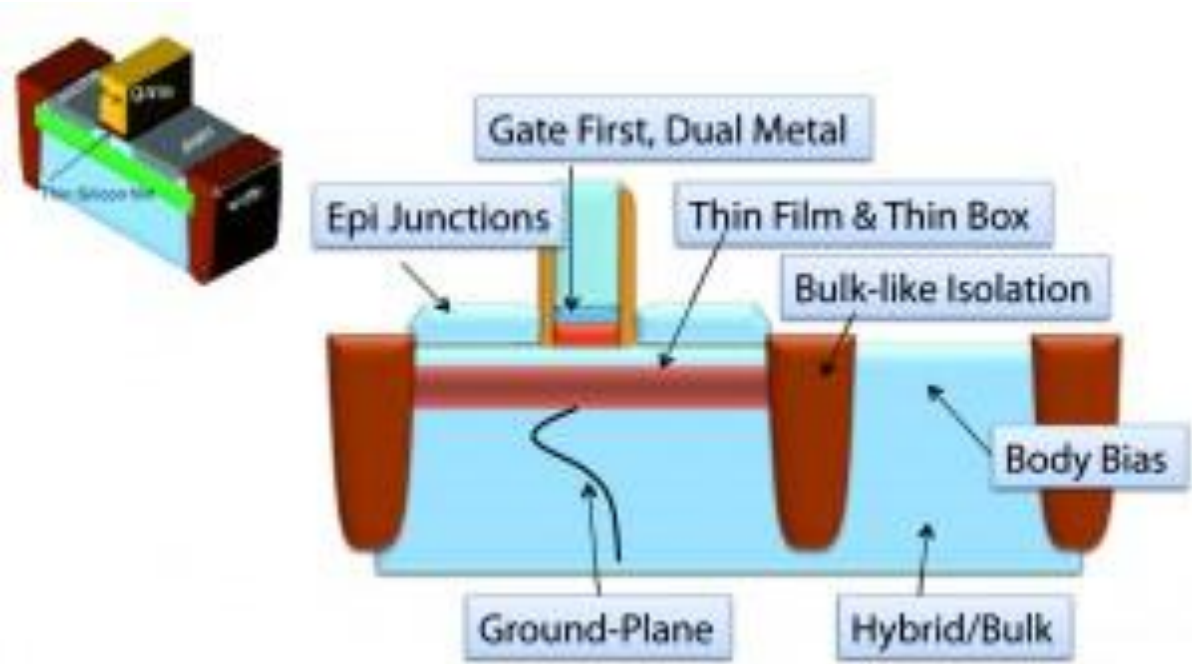
[Makovejev *et al.*, SSE 2012]

The substrate model is of interest particularly for UTBB technology

UTBB Substrate Complexity

Substrate realisation is rather complex in UTBB: GP, wells, p-n junctions

Substrate model becomes very complex

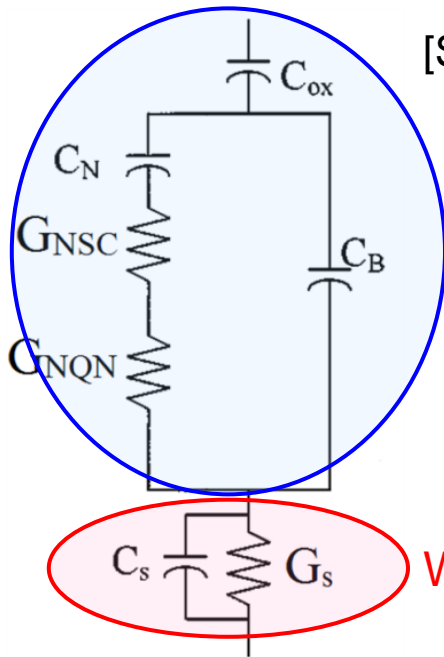


[ST-M]

Motivation and Aim

- Substrate model valid up to ~ 100 GHz has to be included in complete MOSFET model
- Reproduction of g_d and A_v frequency behaviour for analogue and RF

[Schroder *et al.*, TED 2000]



Was considered
(only up to few MHz)

Was neglected

Things changed:

- Thin BOX
- Highly doped GP
- Wells

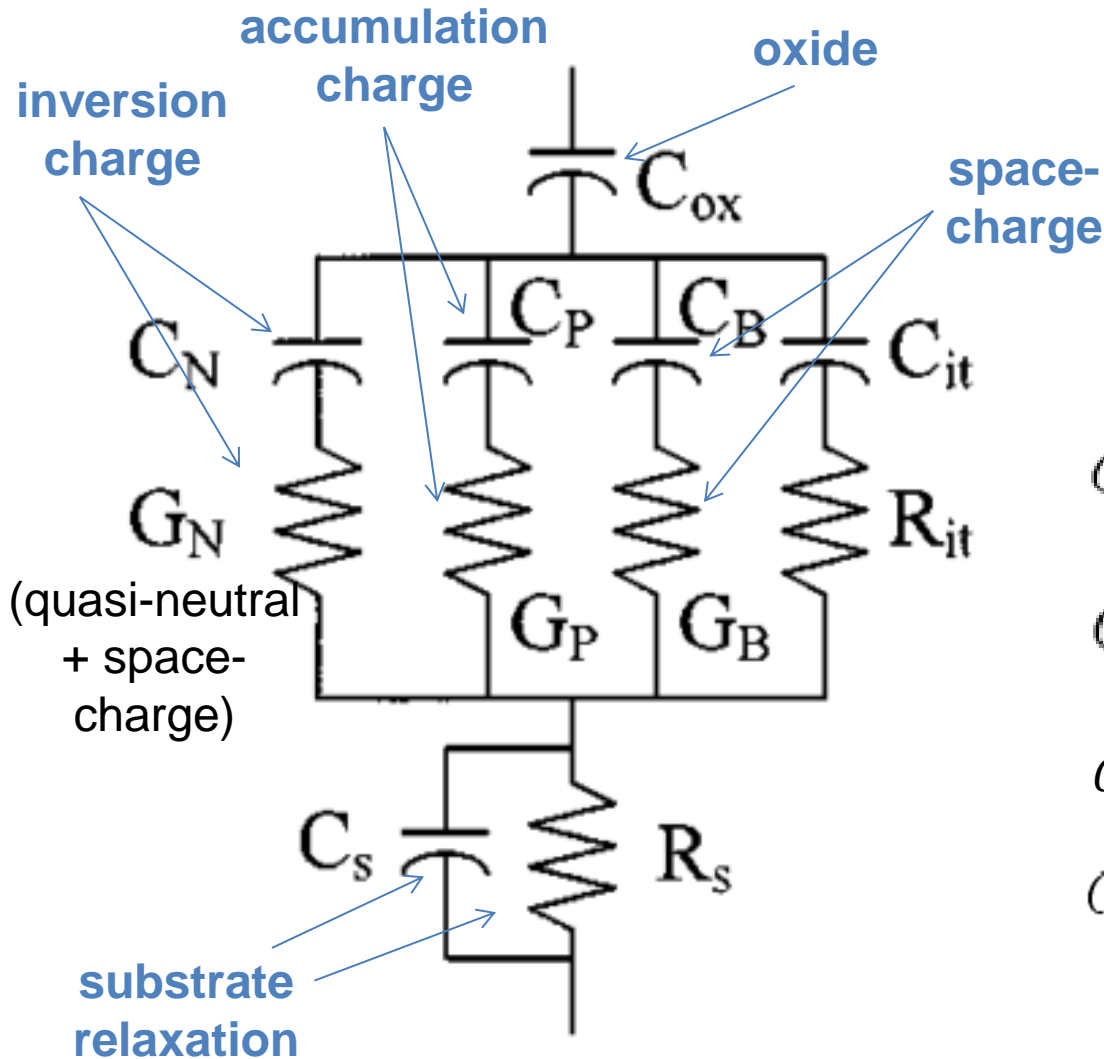
Aim: describe the total substrate impedance

1st step: identify components to be included in the substrate model

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Equivalent Circuit and Fitting



Fitting:

$$C_{ox} = \frac{K_{ox}\epsilon_o A}{t_{ox}};$$

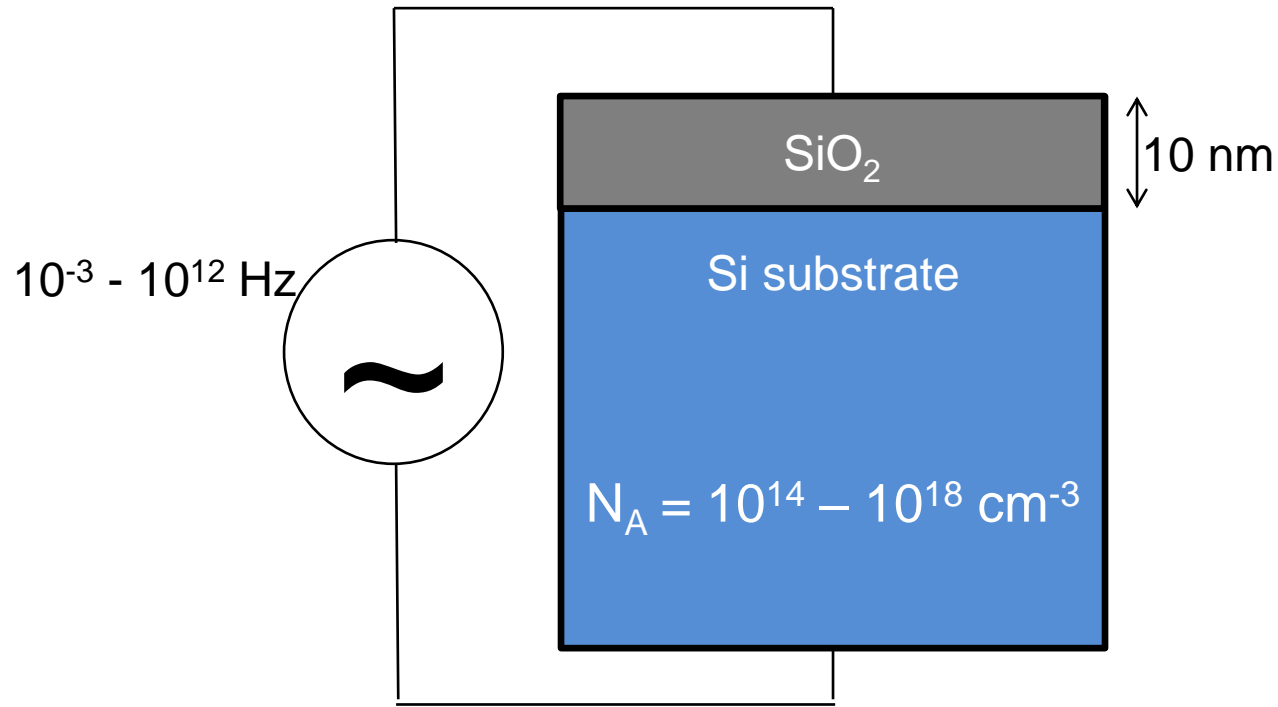
$$C_B = \frac{K_s\epsilon_o A}{W};$$

$$G_s = \frac{Aq(\mu_n n + \mu_p p)}{t}$$

$$G_{N,scr} + G_{N,qnr} = \frac{2K_s\epsilon_o A n_i}{\tau_g N_A W} + \frac{qA\mu_n n_i^2}{N_A L_n}$$

[Schroder *et al.*, TED 2000]

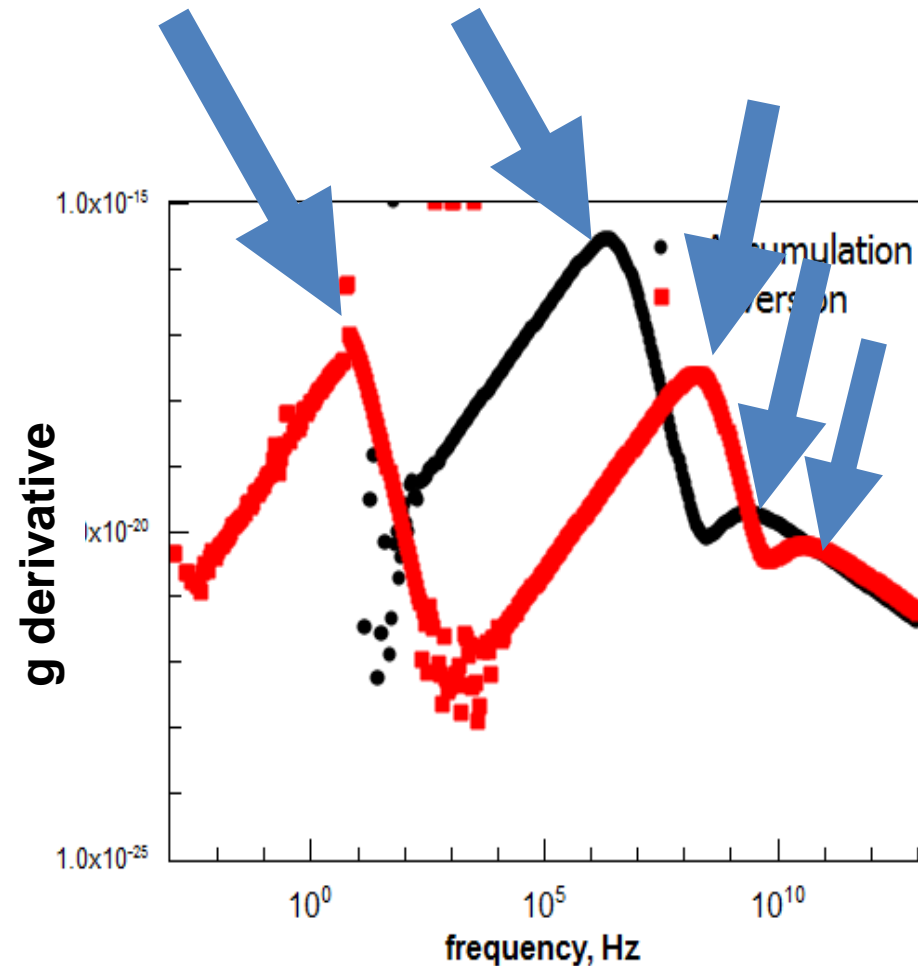
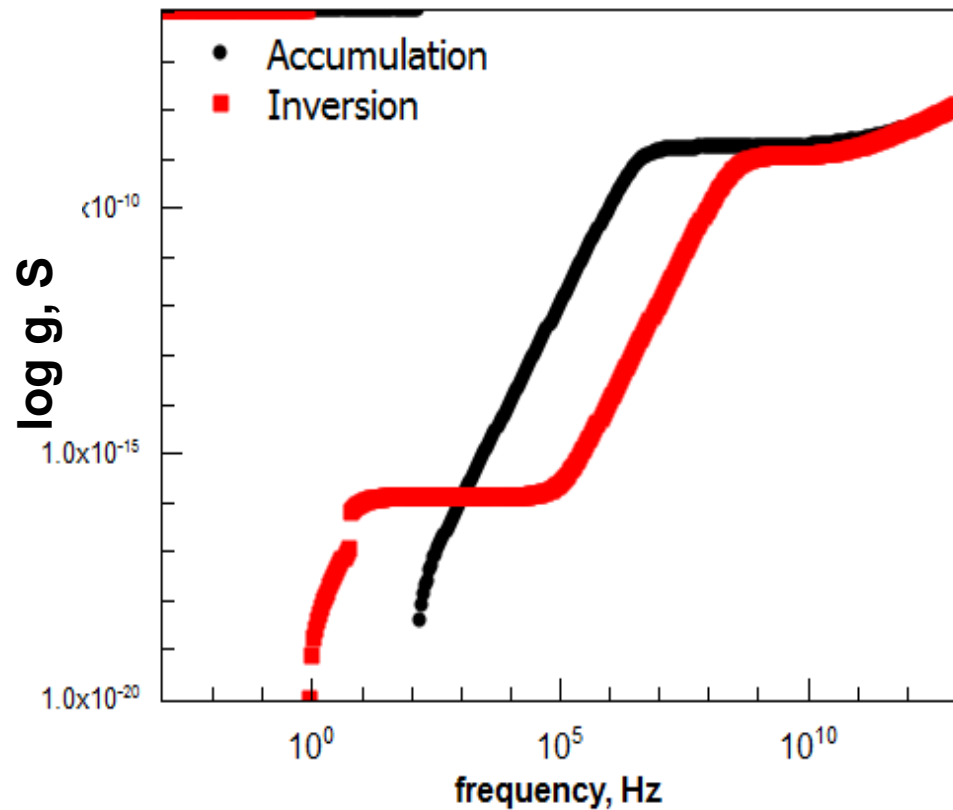
Atlas Simulations



Temperature (300 - 675 K) and **doping** are varied in order to discriminate the mechanisms

Extraction

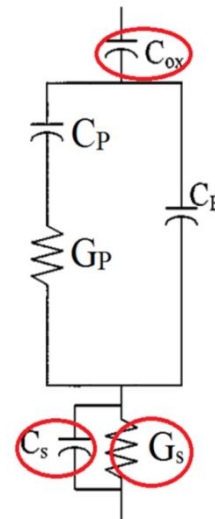
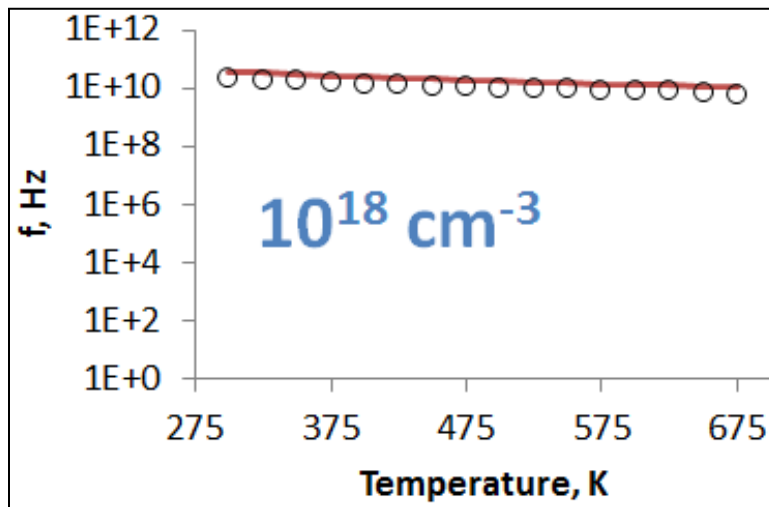
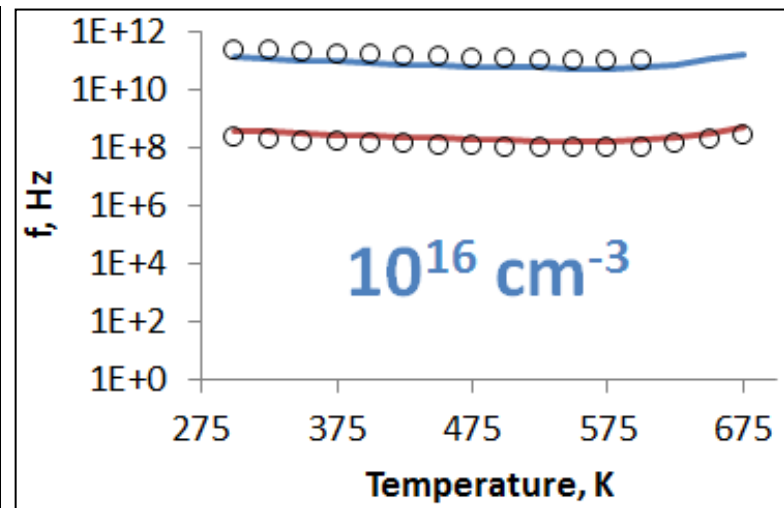
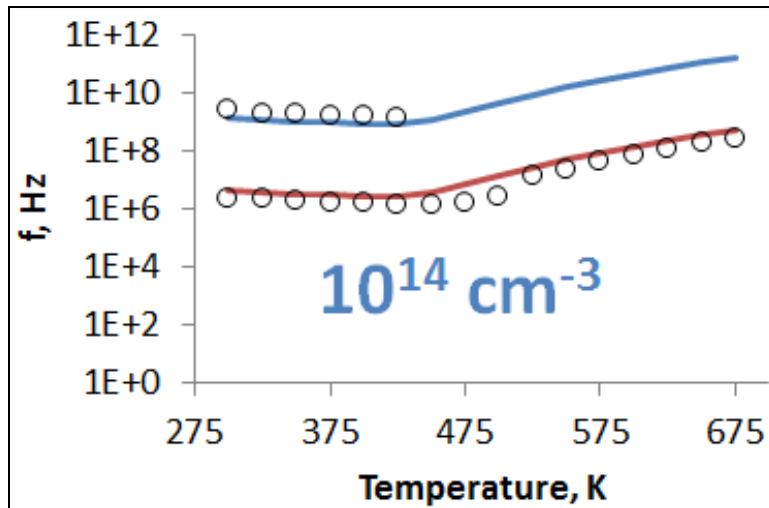
Characteristic frequencies were extracted from peaks of capacitance (or conductance) derivative



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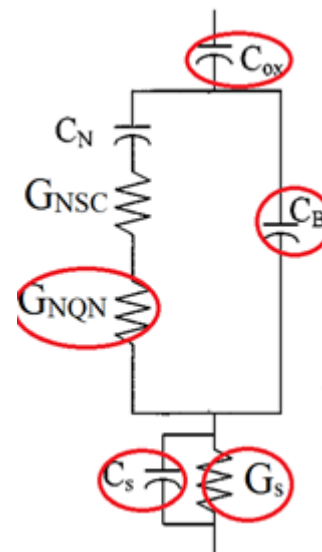
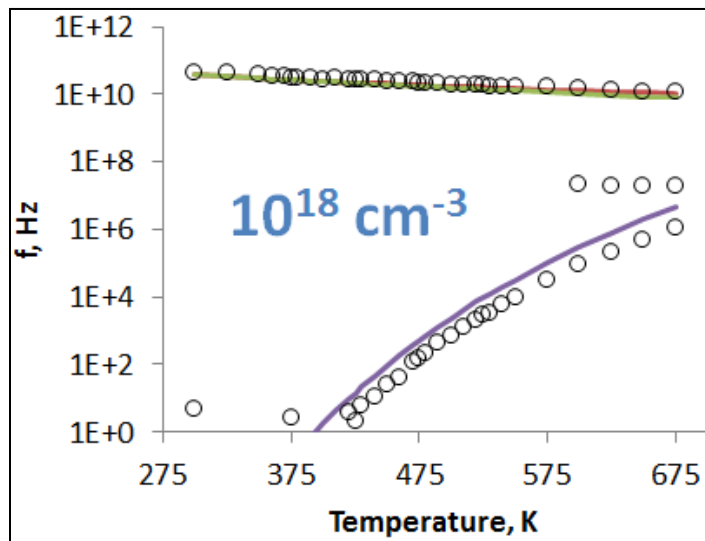
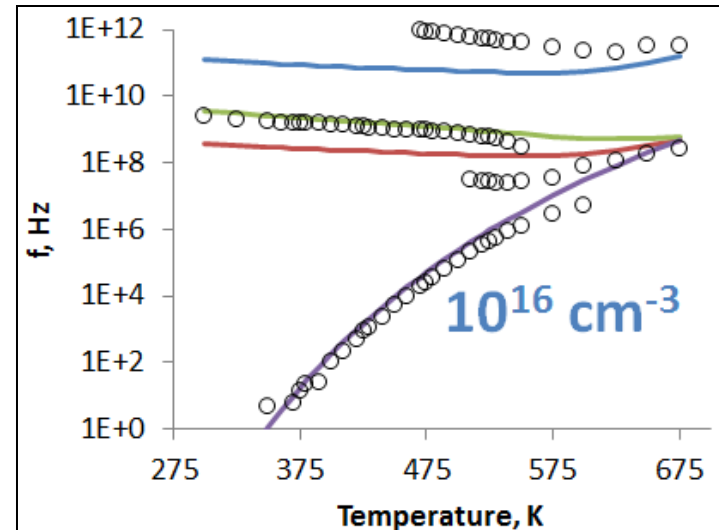
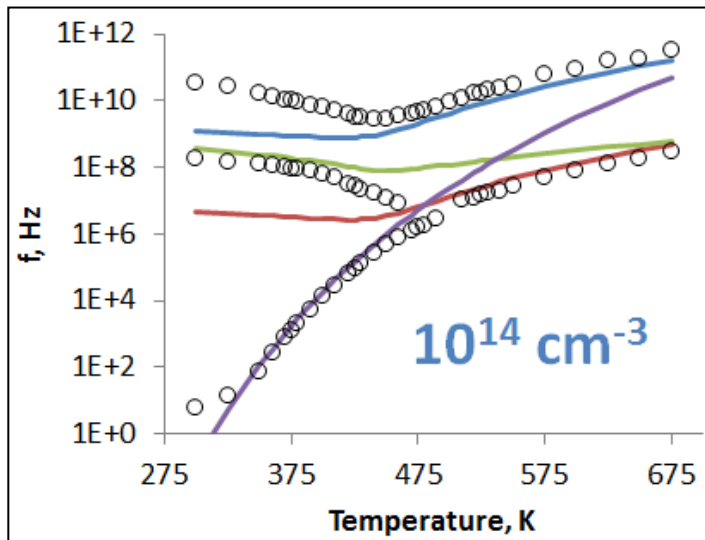
Simulations vs. Model - Accumulation



G_s/C_s and G_s/C_{ox} allow to reproduce simulated frequency behaviour up to 10^{12} Hz

Symbols – simulated characteristic frequencies
Lines - fitting

Simulations vs. Model - Inversion



G_s/C_s , G_s/C_{ox} ,
 G_s/C_b and G_{nqr}/C_{ox}
 allow to reproduce
 simulated
 behaviour up to
 10^{12} Hz

Symbols – simulated characteristic frequencies
Lines - fitting

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Summary and Future Work

- There is a need for a **substrate model** valid up to high frequencies in advanced FDSOI devices
- **Identified components** to be included:
 - In inversion G_s/C_s , G_s/C_{ox} , G_s/C_b and G_{nqn}/C_{ox}
 - In accumulation G_s/C_s and G_s/C_{ox}
- **Future work:**
 - Complex doping profile in substrate
 - MOSFET simulations
 - MOSFET model

The End